

MARKED-UP VERSION OF AMENDED CLAIMS TO SHOW CHANGES

Please amend the claims as follows:

1 1. (Amended) An apparatus comprising:  
2 a die;  
3 a package coupled to the die; and  
4 an interposer, fixedly coupled to the package and formed from a circuit board  
5 substrate, by which the apparatus can be electrically coupled to a circuit board, the  
6 interposer having a first plurality of contacts spaced at a pitch and coupling the  
7 interposer to the package, the interposer further having a second plurality of contacts  
8 spaced at said pitch to couple the interposer to the circuit board.

1 10. (Amended) An interposer comprising:  
2 a circuit board substrate having a first surface and a second surface;  
3 a first plurality of conductive contacts spaced at a pitch on the first surface to be  
4 fixedly coupled to an electronic component package;  
5 a second plurality of conductive contacts spaced at said pitch on the second  
6 surface to be fixedly coupled to a circuit board; and  
7 a plurality of conductive paths, each separately connecting one of the first  
8 plurality of conductive contacts with one of the second plurality of conductive contacts.

1 18. (Amended) An electronic apparatus comprising:  
2 a die having a plurality of electronic circuits formed thereon;

a package substrate having a first surface coupled to the die and a second surface;  
a circuit board; and  
an interposer coupled between the second surface of the package substrate and the circuit board, the interposer comprising  
a circuit board substrate having a first surface and a second surface,  
a first plurality of conductive contacts disposed at a pitch on the first surface of the circuit board substrate, to be fixedly coupled to an electronic component package,  
a second plurality of conductive contacts disposed at said pitch on the second surface of the circuit board substrate, to be coupled to a circuit board, and  
a plurality of conductive paths, each separately connecting one of the first plurality of conductive contacts with one of the second plurality of conductive contacts.

23. (Amended) A method of coupling an electronic circuit package to a circuit board, the method comprising:  
fixedly coupling a plurality of electrical contacts on a first surface of an interposer to the electronic circuit package, the interposer formed from a circuit board substrate having the first surface, a second surface, and a plurality of conductive paths from the first surface to the second surface; and  
fixedly coupling a plurality of electrical contacts on the second surface to the circuit board, the interposer such that the first plurality of electrical contacts and the second plurality of electrical contacts are spaced at an equal pitch.